

PHOTOCOUPLER PS2581L1,PS2581L2

LONG CREEPAGE TYPE HIGH ISOLATION VOLTAGE 4-PIN PHOTOCOUPLER

-NEPOC Series-

DESCRIPTION

The PS2581L1, PS2581L2 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor in a plastic DIP (Dual In-line Package).

Creepage distance and clearance of leads are over 8 millimeters.

The PS2581L2 is lead bending type (Gull-wing) for surface mounting.

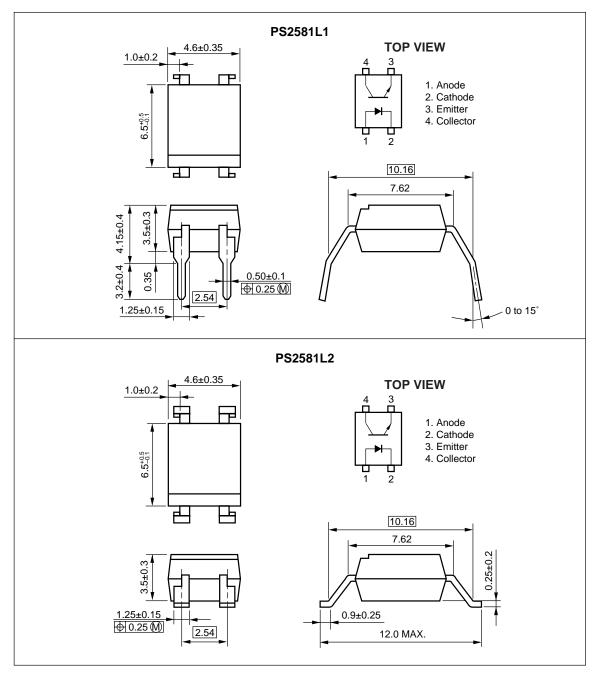
FEATURES

- Long creepage and clearance distance (8 mm)
- High isolation voltage (BV = 5 000 Vr.m.s.)
- High collector to emitter voltage (VCEO = 80 V)
- High-speed switching ($t_r = 3 \mu s TYP$., $t_f = 5 \mu s TYP$.)
- High current transfer ratio (CTR = 200 % TYP.)
- Safety standards
 - UL approved: File No. E72422
 - CSA approved: No. CA101391
 - BSI approved: No. 8243/8244
 - NEMKO approved: No. P97103006
 - DEMKO approved: No. 307269
 - SEMKO approved: No. 304666
 - FIMKO approved: No. FI 19424
 - DIN EN60747-5-2 (VDE0884 Part2) approved

APPLICATIONS

- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

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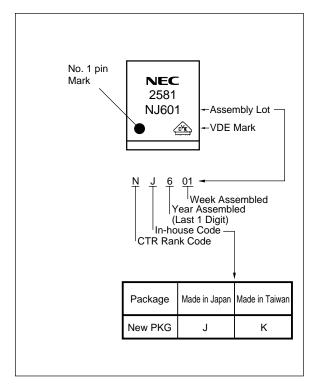


PACKAGE DIMENSIONS (in millimeters)

PHOTOCOUPLER CONSTRUCTION

Parameter	Unit (MIN.)
Air Distance	8 mm
Outer Creepage Distance	8 mm
Inner Creepage Distance	4 mm
Isolation Distance	0.4 mm

★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *1
PS2581L1	PS2581L1-A	Pb-Free	Magazine case 100 pcs	Standard products	PS2581L1
PS2581L2	PS2581L2-A			(UL, CSA, BSI, NEMKO,	PS2581L2
PS2581L2-E3	PS2581L2-E3-A		Embossed Tape 1 000 pcs/reel	SEMKO, DEMKO, FIMKO,	
PS2581L2-E4	PS2581L2-E4-A			DIN EN60747-5-2	
				(VDE0884 Part2)	
				Approved products)	

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit
Diode	Forward Current (DC)	١F	80	mA
	Reverse Voltage	VR	6	V
	Power Dissipation Derating	⊿Po/°C	1.5	mW/°C
	Power Dissipation	PD	150	mW
	Peak Forward Current ^{*1}	IFP	1	А
Transistor	Collector to Emitter Voltage	VCEO	80	V
	Emitter to Collector Voltage	VECO	7	V
	Collector Current	lc	50	mA
	Power Dissipation Derating	⊿Pc/°C	1.5	mW/°C
	Power Dissipation	Pc	150	mW
Isolation Vo	oltage *2	BV	5 000	Vr.m.s.
Operating A	Ambient Temperature	TA	–55 to +100	°C
Storage Ten	nperature	Tstg	–55 to +150	°C

***1** PW = 100 *µ*s, Duty Cycle = 1%

*2 AC voltage for 1 minute at $T_A = 25^{\circ}$ C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.17	1.4	V
	Reverse Current	Ir	Vr = 5 V			5	μA
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		50		pF
Transistor	Collector to Emitter Dark Current	ICEO	V _{CE} = 80 V, I _F = 0 mA			100	nA
Coupled	Current Transfer Ratio (Ic/IF) *1	CTR	IF = 5 mA, VCE = 5 V	80	200	400	%
	Collector Saturation Voltage	Vce(sat)	IF = 10 mA, Ic = 2 mA			0.3	V
	Isolation Resistance	R ⊦o	VI-0 = 1.0 kVDC	10 ¹¹			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time ^{*2}	tr	Vcc = 10 V, lc = 2 mA,		3		μS
	Fall Time ^{*2}	tr	R∟ = 100 Ω		5		

*1 CTR rank

L : 200 to 400 (%)

M : 80 to 240 (%)

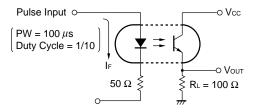
D : 100 to 300 (%)

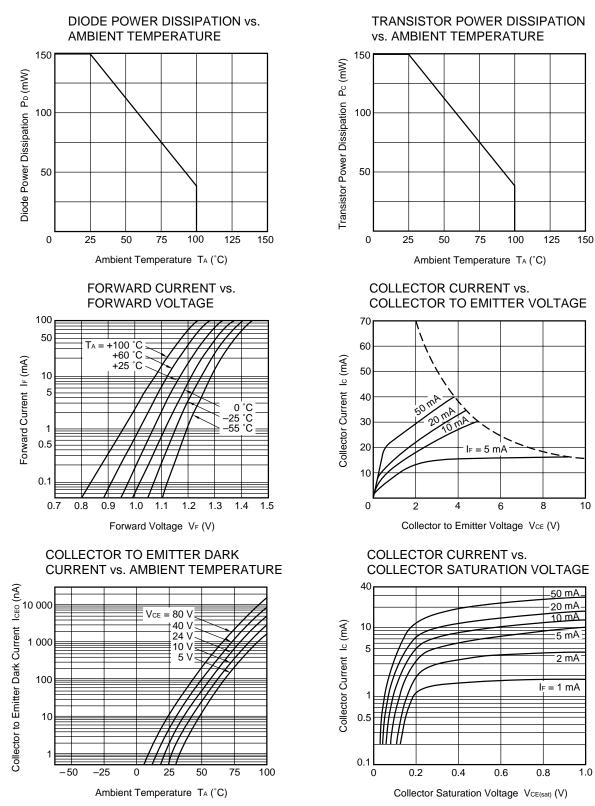
H : 80 to 160 (%)

W : 130 to 260 (%)

N : 80 to 400 (%)

*2 Test circuit for switching time

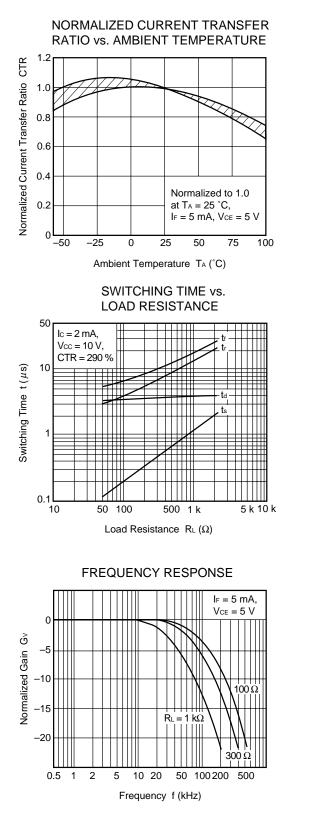


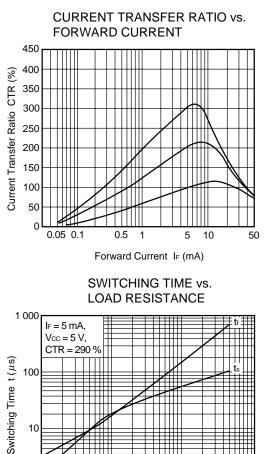


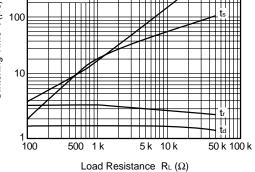
TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

Remark The graphs indicate nominal characteristics.

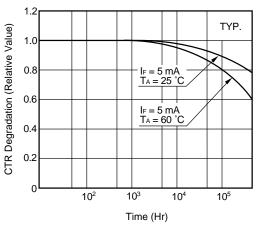
Data Sheet PN10239EJ02V0DS





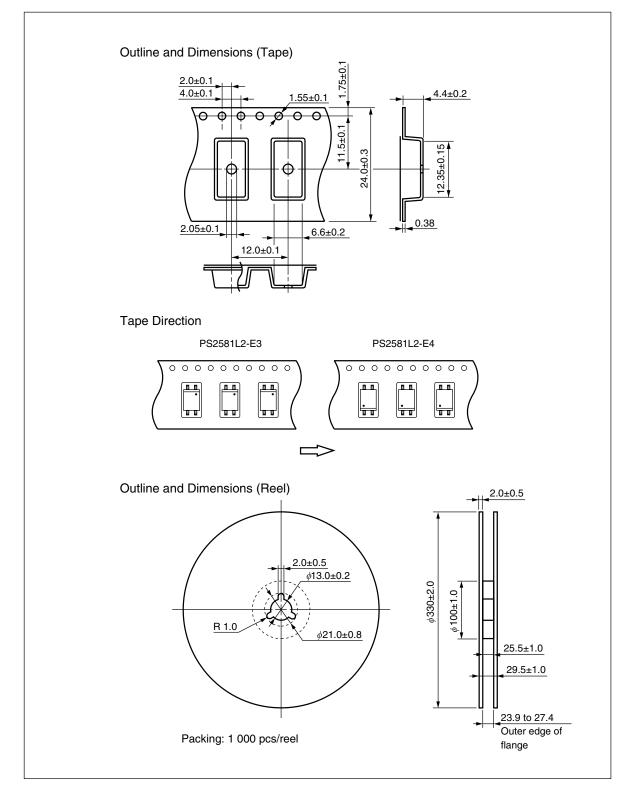


LONG TERM CTR DEGRADATION



Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (in millimeters)



NOTES ON HANDLING

1. Recommended soldering conditions

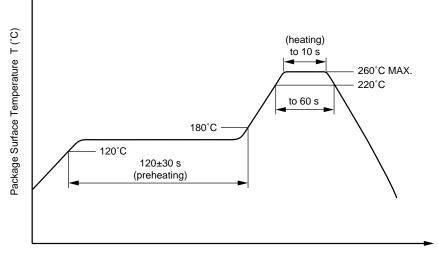
(1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

260°C or below (package surface temperature)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

★ (3) Soldering by soldering iron

Peak temperature (lead part temperature)	350°C or below
 Time (each pins) 	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a
	maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

* 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below $I_F = 1$ mA.

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.

2. Avoid storage at a high temperature and high humidity.

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (VDE0884)

Parameter	Symbol	Speck	Unit
Application classification (DIN VDE 0109) for rated line voltages \leq 300 Vr.m.s. for rated line voltages \leq 600 Vr.m.s.		IV III	
Climatic test class (DIN IEC 68 Teil 1/09.80)		55/100/21	
Dielectric strength maximum operating isolation voltage. Test voltage (partial discharge test procedure a for type test and random test) $U_{pr} = 1.2 \times U_{IORM}, P_d < 5 pC$	Uiorm Upr	890 1 068	V _{peak} V _{peak}
Test voltage (partial discharge test procedure b for all devices test) U_{pr} = 1.6 × U _{IORM} , Pd < 5 pC	Upr	1 424	V _{peak}
Highest permissible overvoltage	Utr	8 000	Vpeak
Degree of pollution (DIN VDE 0109)		2	
Clearance distance		> 8.0	mm
Creepage distance		> 8.0	mm
Comparative tracking index (DIN IEC 112/VDE 0303 part 1)	СТІ	175	
Material group (DIN VDE 0109)		lli a	
Storage temperature range	Tstg	-55 to +150	°C
Operating temperature range	TA	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at } T_A = 25 \text{ °C}$ $V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100 \text{ °C}$	Ris MIN. Ris MIN.	10 ¹² 10 ¹¹	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature	Tsi	175	°C
Current (input current I⊧, Psi = 0) Power (output or total power dissipation) Isolation resistance	lsi Psi	400 700	mA mW
V_{IO} = 500 V dc at T _A = 175 °C (Tsi)	Ris MIN.	10 ⁹	Ω

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M8E 00.4-0110

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	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	• Do not lick the product or in any way allow it to enter the mouth.

► For further information, please contact

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CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices	
Lead (Pb)	< 1000 PPM	-A -AZ Not Detected (*)	
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
РВВ	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

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